

Single N-Channel MOSFET

DESCRIPTION

SMC3206H is the N-Channel enhancement mode power field effect transistors, provide superior fast switching performance and withstand high energy pulse in the avalanche and commutation mode.

PART NUMBER INFORMATION

SMC 3206 H - TR G
 a b c d e

a : Company name.
 b : Product Serial number.
 c : Package code H:TO-252
 d : Handling code TR:Tape&Reel
 e : Green produce code G:RoHS Compliant

FEATURES

$V_{DS}=30V$, $I_D=100A$

$R_{DS(ON)}=2.7m\Omega(Typ.)@V_{GS}=10V$

$R_{DS(ON)}=3.4m\Omega(Typ.)@V_{GS}=4.5V$

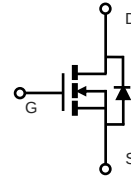
- ◆ High power and current handling capability
- ◆ 100% EAS Guaranteed

APPLICATIONS

- ◆ DC/DC Converter
- ◆ Power Management



TO-252



ABSOLUTE MAXIMUM RATINGS ($T_A=25^{\circ}C$ Unless otherwise noted)

Symbol	Parameter	Rating	Units
V_{DSS}	Drain-Source Voltage	30	V
V_{GSS}	Gate-Source Voltage	± 20	V
I_D	Continuous Drain Current *	$T_C=25^{\circ}C$	100
		$T_C=100^{\circ}C$	72.5
I_{DM}	Pulsed Drain Current ^B	280	A
I_D	Continuous Drain Current	$T_A=25^{\circ}C$	22
		$T_A=70^{\circ}C$	17.5
P_D	Power Dissipation ^A	$T_A=25^{\circ}C$	2.5
		$T_A=70^{\circ}C$	1.6
I_{AS}	Single Pulse Avalanche Current ^B	45	A
E_{AS}	Single Pulse Avalanche energy $L=0.1mH$ ^{BE}	101	mJ
P_D	Power Dissipation ^C	$T_C=25^{\circ}C$	69
		$T_C=100^{\circ}C$	28
T_J	Operation Junction Temperature	-55/150	$^{\circ}C$
T_{STG}	Storage Temperature Range	-55/150	$^{\circ}C$

THERMAL RESISTANCE

Symbol	Parameter	Typ	Max	Units
$R_{\theta JA}$	Thermal Resistance Junction to Ambient ^A	$t \leq 10s$	20	$^{\circ}C/W$
	Thermal Resistance Junction to Ambient ^{AC}	Steady-State	50	
$R_{\theta JC}$	Thermal Resistance Junction to Case		1.8	

ELECTRICAL CHARACTERISTICS ($T_A=25^{\circ}\text{C}$ Unless otherwise noted)

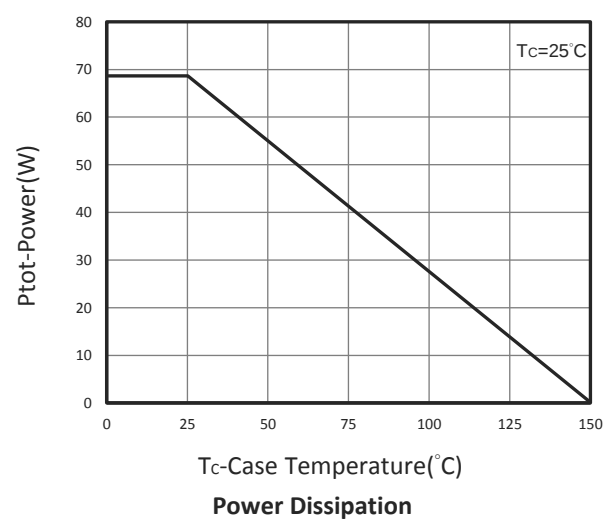
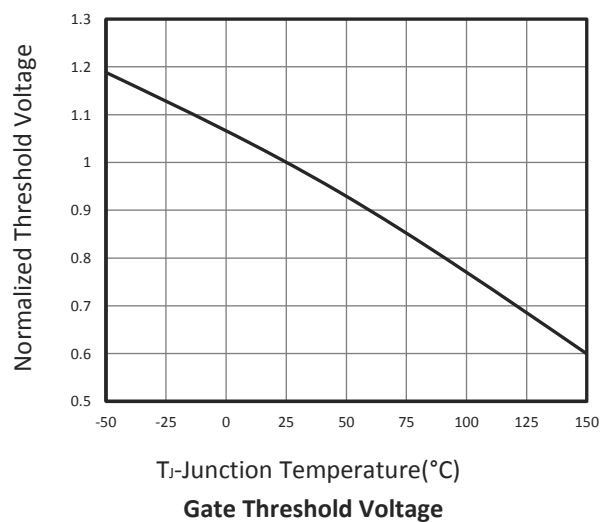
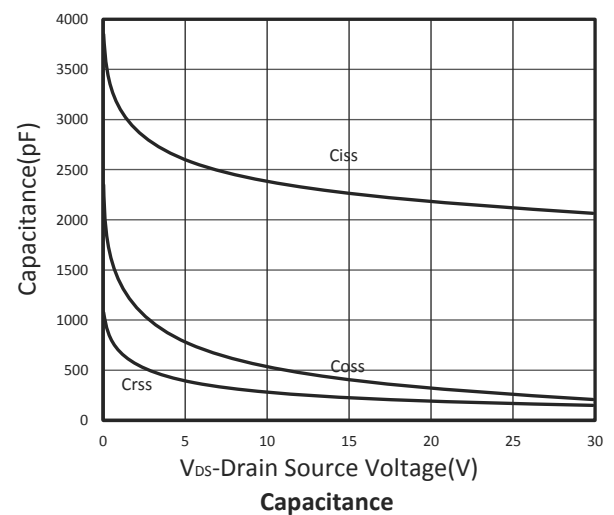
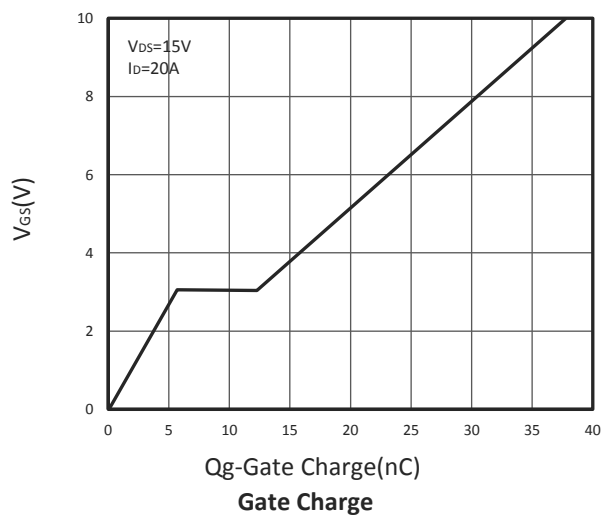
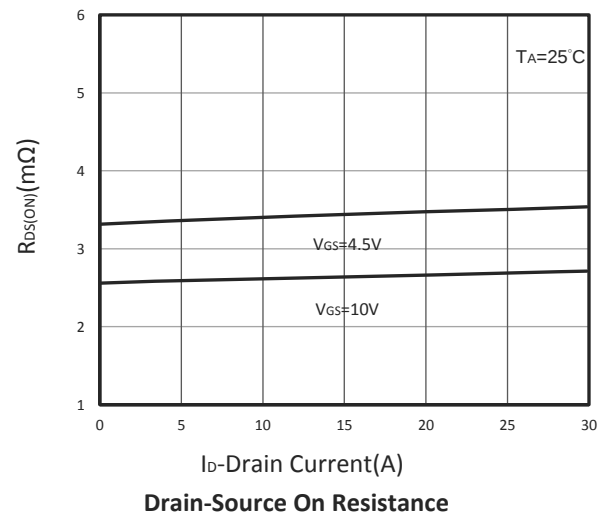
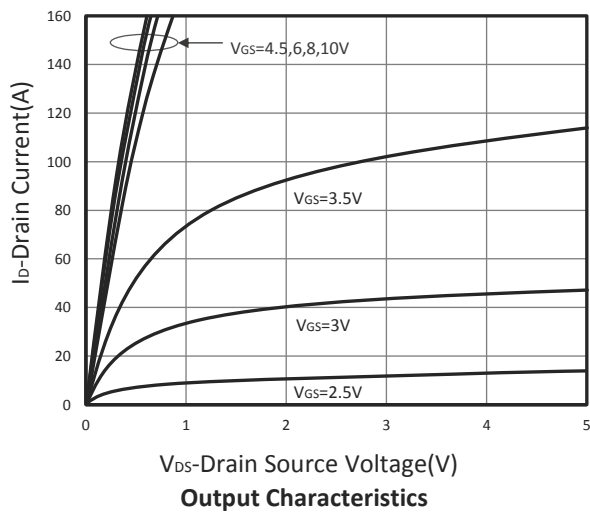
Symbol	Parameter	Condition	Min	Typ	Max	Unit
Static Parameters						
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =250μA	30			V
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =250μA	1.2	1.6	2.5	V
I _{GSS}	Gate Leakage Current	V _{DS} =0V, V _{GS} =±20V			±100	nA
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =30V, V _{GS} =0V, T _J =25°C			-1	μA
		V _{DS} =24V, V _{GS} =0V, T _J =75°C			-10	
R _{DS(ON)}	Drain-source On-Resistance [Ⓟ]	V _{GS} =10V, I _D =20A V _{GS} =4.5V, I _D =15A		2.7 3.4	3.2 4.2	mΩ
G _{fs}	Forward Transconductance	V _{DS} =5V, I _D =20A		72		S
Diode Characteristics						
V _{SD}	Diode Forward Voltage [Ⓟ]	I _S =1A, V _{GS} =0V			1	V
I _S	Diode Continuous Forward Current				80	A
t _{rr}	Reverse Recovery Time	I _S =20A, dI/dt=100A/μs		34		ns
Q _{rr}	Reverse Recovery Charge			25		nC
Dynamic and Switching Parameters [Ⓕ]						
Q _g	Total Gate Charge	V _{DS} =15V, V _{GS} =10V, I _D =20A		37.5	52.5	nC
Q _g	Total Gate Charge (4.5V)			17.5	24.5	
Q _{gs}	Gate-Source Charge			5.4	7.6	
Q _{gd}	Gate-Drain Charge			6.7	9.4	
C _{iss}	Input Capacitance	V _{DS} =15V, V _{GS} =0V, f=1MHz		2250		pF
C _{oss}	Output Capacitance			315		
C _{rss}	Reverse Transfer Capacitance			168		
R _g	Gate Resistance	V _{GS} =0V, V _{DS} =0V, f=1MHz		2		Ω
t _{d(on)}	Turn-On Time	V _{DD} =15V, V _{GS} =10V, R _G =3Ω I _D =1A		8		nS
t _r				5		
t _{d(off)}	Turn-Off Time			23		
t _f				9		

Note: Absolute maximum ratings are those values beyond which the device could be permanently damaged.

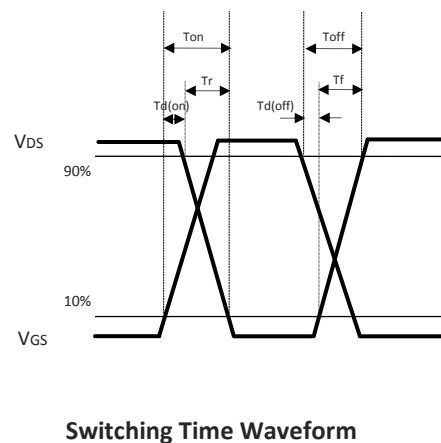
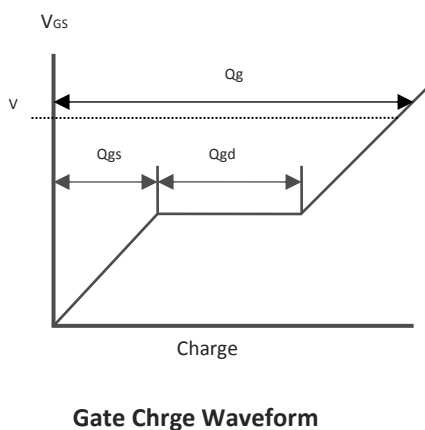
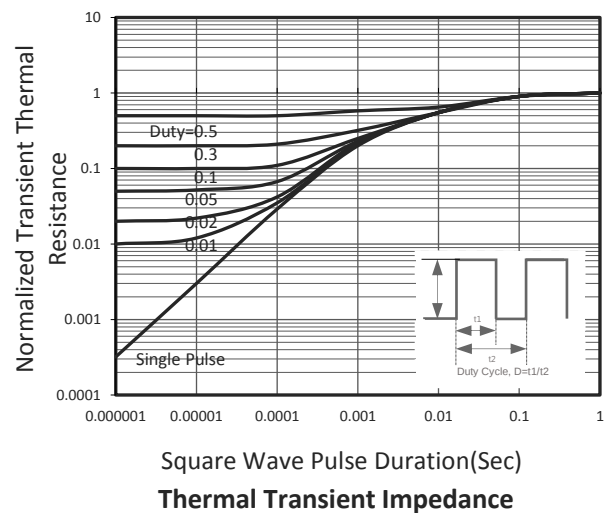
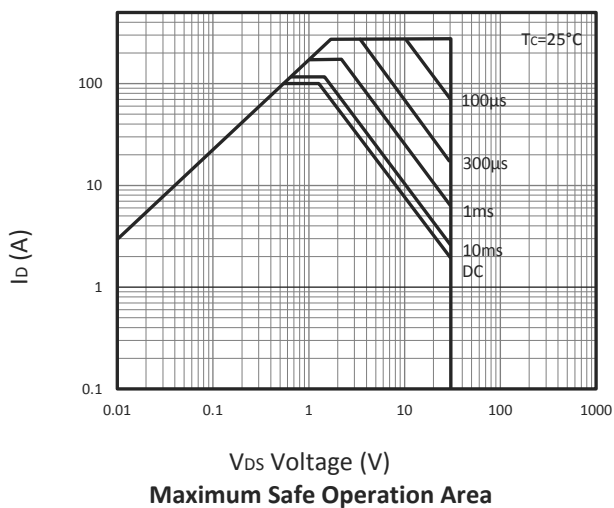
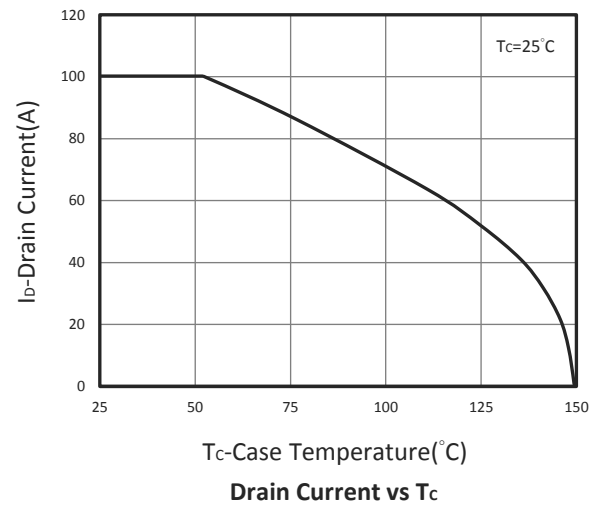
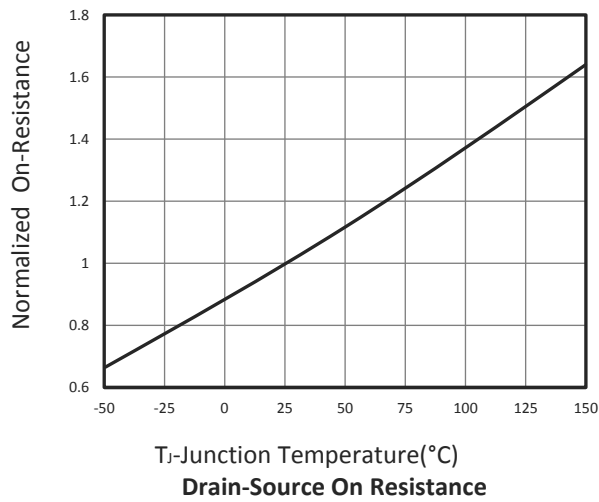
- A. Surface mounted on FR4 board using 1 in² pad size.
- B. Pulsed width limited by maximum junction temperature, $T_{J(MAX)}=150^{\circ}\text{C}$ (initial temperature $T_J=25^{\circ}\text{C}$).
- C. Using $\leq 10s$ junction-to-ambient thermal resistance is base on $T_{J(MAX)}=150^{\circ}\text{C}$.
- D. Pulse test width $\leq 300\mu s$ and duty cycle $\leq 2\%$.
- E. The EAS data shows maximum, The test condition is $V_{DD}=25V, V_{GS}=10V, L=0.1mH, I_{AS}=45A$
- F. Guaranteed by design, not subject to production testing.
- *. The maximum rating current limited by package.

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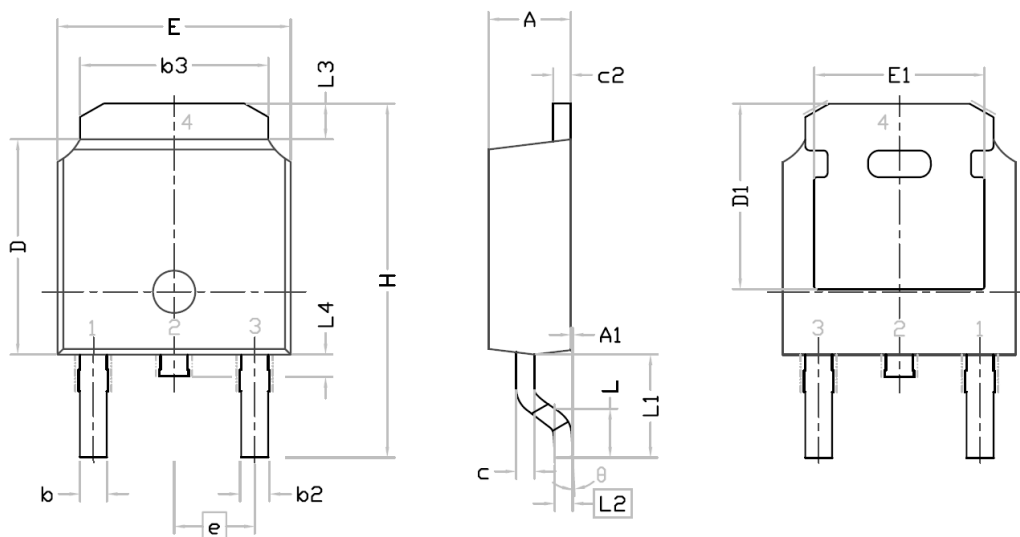
TYPICAL CHARACTERISTICS



TYPICAL CHARACTERISTICS



TO-252 PACKAGE DIMENSIONS



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	2.200	2.380	0.087	0.094
A1	0.000	0.127	0.000	0.005
b	0.640	0.880	0.025	0.035
b2	0.770	1.140	0.030	0.045
b3	5.210	5.460	0.205	0.215
c	0.460	0.600	0.018	0.024
c2	0.460	0.580	0.018	0.023
D	6.000	6.223	0.236	0.245
D1	5.210	-	0.205	-
E	6.400	6.731	0.252	0.265
E1	4.400	-	0.173	-
e	2.286 BSC.		0.090 BSC.	
H	9.400	10.40	0.370	0.409
L	1.400	1.770	0.055	0.070
L1	2.743 REF.		0.108 REF.	
L2	0.508 BSC.		0.020 BSC.	
L3	0.890	1.270	0.035	0.050
L4	0.640	1.010	0.025	0.040
Θ	0°	10°	0°	10°

Recommended Land Pattern

